

RoHS Compliant Product  
A suffix of "-C" specifies halogen free

## DESCRIPTION

The SMS501DE is the highest performance trench N-ch MOSFETs with extreme high cell density , which provide excellent  $R_{DS(on)}$  and gate charge for most of the synchronous buck converter applications .

## FEATURES

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- Green Device Available

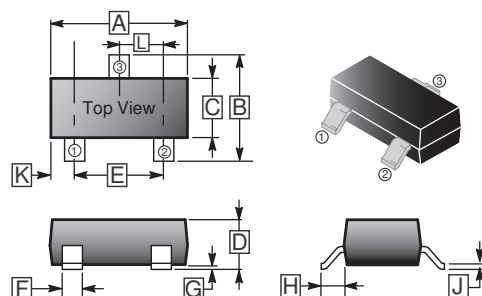
## MARKING

501DE

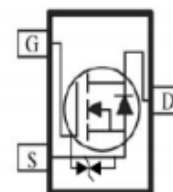
## PACKAGE INFORMATION

Package	MPQ	Leader Size
SOT-23	3K	7 inch

## SOT-23



REF.	Millimeter		REF.	Millimeter	
	Min.	Max.		Min.	Max.
A	2.70	3.10	G	0.09	0.18
B	2.10	2.65	H	0.35	0.65
C	1.20	1.40	J	0.08	0.20
D	0.89	1.15	K	0.6 REF.	
E	1.78	2.04	L	0.95 BSC.	
F	0.30	0.50			



## ABSOLUTE MAXIMUM RATINGS ( $T_A=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	$V_{DS}$	600	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current	$I_D$	$T_C=25^\circ\text{C}$	0.03
		$T_C=100^\circ\text{C}$	0.024
Pulsed Drain Current	$I_{DM}$	0.12	A
Total Power Dissipation	$P_D$	$T_C=25^\circ\text{C}$	0.5
		Derate above $25^\circ\text{C}$	0.004
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55~150	$^\circ\text{C}$
<b>Thermal Resistance Rating</b>			
Maximum Thermal Resistance Junction-Ambient	$R_{\theta JA}$	250	$^\circ\text{C} / \text{W}$
Maximum Thermal Resistance Junction-Case	$R_{\theta JC}$	50	$^\circ\text{C} / \text{W}$

**ELECTRICAL CHARACTERISTICS** ( $T_J = 25^\circ\text{C}$  unless otherwise specified)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Teat Conditions
<b>Static</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	600	-	-	V	$V_{GS}=5V, I_D=250\mu A$
Drain-Source Leakage Current	$I_{D(OFF)}$	-	-	0.1	$\mu A$	$V_{GS}=5V, V_{DS}=600V$
Gate-Source Leakage Current	$I_{GSS}$	-	-	$\pm 100$	nA	$V_{GS}=\pm 20V$
Gate-Threshold Voltage	$V_{GS(th)}$	-2.7	-	-1	V	$V_{DS}=3V, I_D=8\mu A$
Drain-Source Leakage Current	$I_{DSS}$	12	-	-	mA	$V_{DS}=25V, V_{GS}=0$
Static Drain-Source On-Resistance	$R_{DS(ON)}$	-	310	700	$\Omega$	$V_{GS}=0V, I_D=3mA$
		-	330	700		$V_{GS}=10V, I_D=16mA$
Total Gate Charge <sup>1,2</sup>	$Q_g$	-	1.8	-	nC	$I_D=0.01A$ $V_{DS}=4000V$ $V_{GS}=5V$
Gate-Source Charge <sup>1,2</sup>	$Q_{gs}$	-	0.75	-		
Gate-Drain Change <sup>1,2</sup>	$Q_{gd}$	-	0.56	-		
Turn-on Delay Time <sup>1,2</sup>	$T_{d(on)}$	-	18	-	nS	$V_{DD}=300V$ $I_D=0.01A$ $V_{GS}=-5V$ $V_{GS}=7V$ $R_G=6\Omega$
Rise Time <sup>1,2</sup>	$T_r$	-	90	-		
Turn-off Delay Time <sup>1,2</sup>	$T_{d(off)}$	-	93	-		
Fall Time <sup>1,2</sup>	$T_f$	-	210	-		
Input Capacitance	$C_{iss}$	-	99	-	pF	$V_{GS}=5V$ $V_{DS}=25V$ $f=1.0MHz$
Output Capacitance	$C_{oss}$	-	9.1	-		
Reverse Transfer Capacitance	$C_{rss}$	-	5	-		
<b>Source-Drain Diode</b>						
Diode Forward Voltage	$V_{SD}$	-	-	1.2	V	$I_S=16mA, V_{GS}=5v$
Continuous Source Current	$I_S$	-	-	0.03	A	Integral Reverse P-N Junction Diode in the MOSFET
Pulsed Source Current	$I_{SM}$	-	-	0.12	A	
Reverse Recovery Time	$T_{rr}$	-	-	367	ns	$I_F=0.01A, V_R=300V,$ $di_F/dt=100A/\mu S$
Reverse Recovery Charge	$Q_{rr}$	-	-	963	$\mu C$	

Notes:

1. Pulse Test: Pulse width  $\leq 300\mu S$ , Duty cycle  $\leq 2\%$
2. Essentially independent of operating temperature.

**CHARACTERISTIC CURVES**

Figure 1. On-Region Characteristics

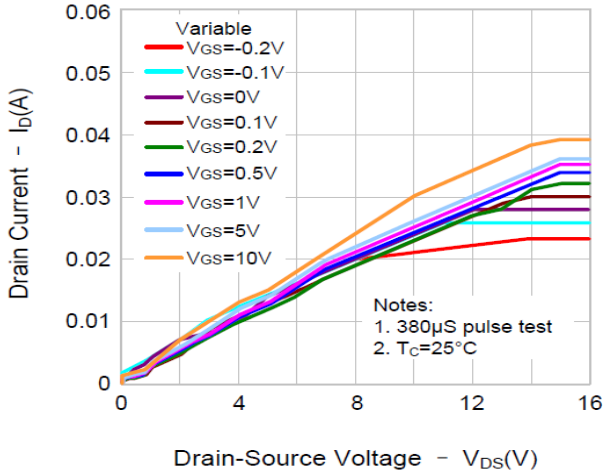


Figure 2. Transfer Characteristics

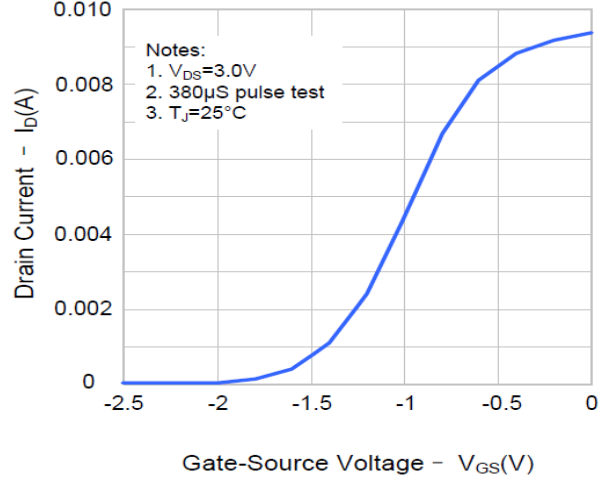


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

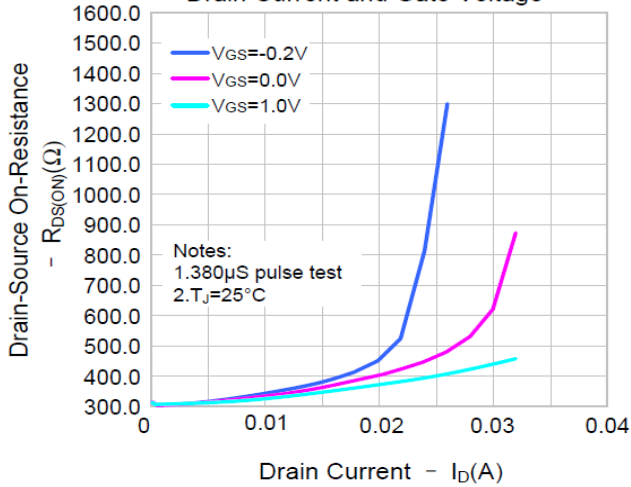


Figure 4. Forward characteristics of reverse diode

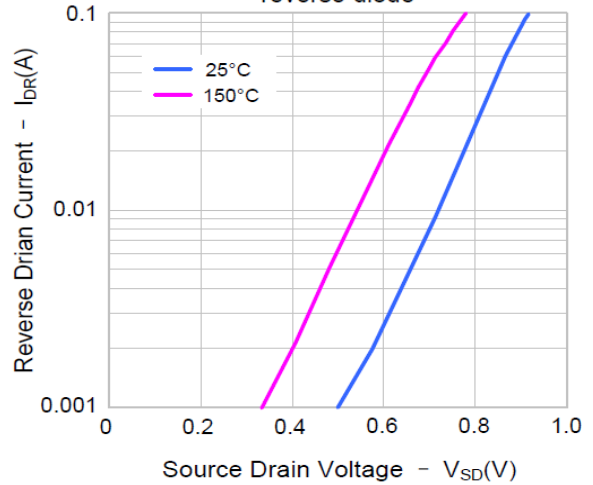


Figure 5. Breakdown Voltage Variation vs. Temperature

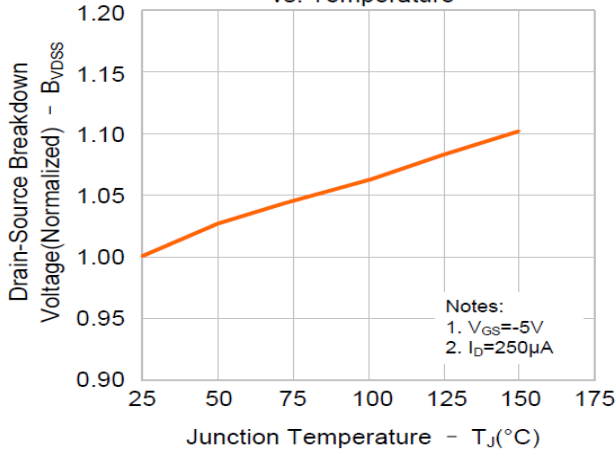
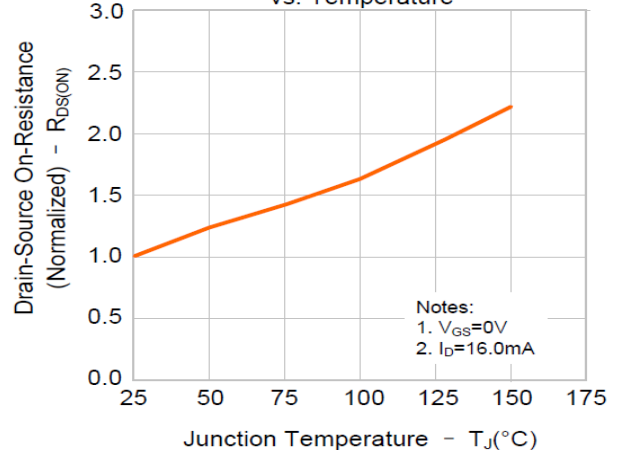


Figure 6. On-resistance Variation vs. Temperature



**CHARACTERISTIC CURVES**

Figure 7. Gate Threshold Voltage vs. Temperature

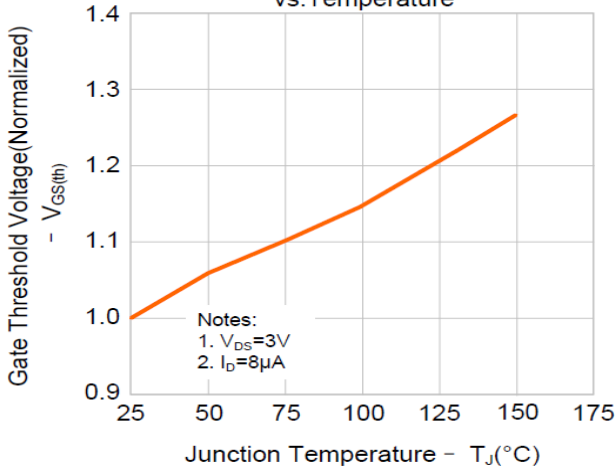


Figure 8. Typ. Forward Transconductance

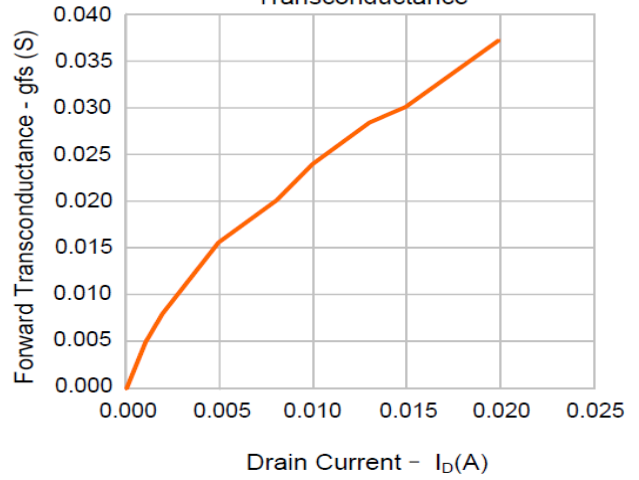


Figure 9. Power Dissipation vs. Case Temperature

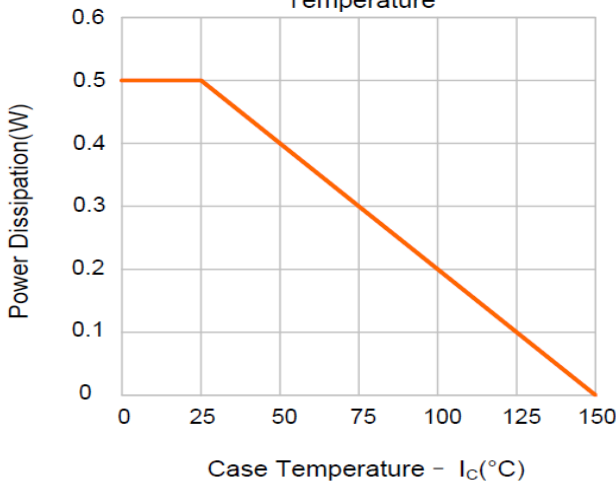


Figure 10. Max. Safe Operating Area

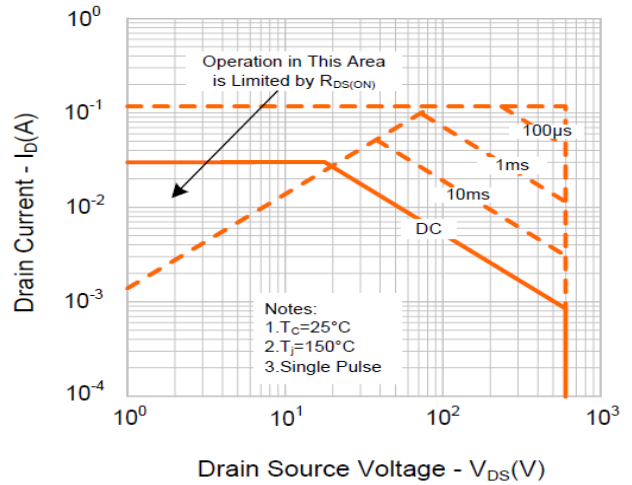


Figure 11. Maximum Drain Current vs. Case Temperature

